

Currentless Copper Tinning Preparation

A high-quality currentless (chemical) bath for printed circuits. It creates hermetic, glossy, 5–12 µm thick coatings with very good adhesion. The preparation provides protection against harmful effect of air and moisture.

Way of application:	
45 g for 0,5 l water	90 g for 1,0 l water
1. Package contents dissolve in 0.5 l of water at a temperature 80–90 °C (recommended to use of distilled or demineralized water).	1. Package contents dissolve in 1.0 l of water at a temperature 80–90 °C (recommended to use of distilled or demineralized water).
2. Stir until fully dissolved solution, allow to cool to temperature room.	
3. Clean your board carefully.	
4. Tin by immersion in compiling at temperature 20–30°C for 5 minutes to few hours depending on the desired film thickness (max 12 µm).	
5. Thoroughly rinse the board (first in cold then in hot water) and dry.	